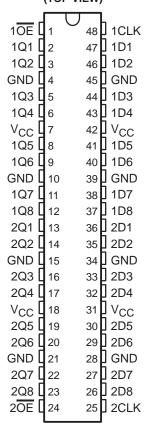
SCBS205C - MARCH 1993 - REVISED MAY 1997

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB*™ BiCMOS Design Significantly Reduces Power Dissipation
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

description

The 'ABT16374A are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

SN54ABT16374A . . . WD PACKAGE SN74ABT16374A... DGG OR DL PACKAGE (TOP VIEW)



These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components

OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16374A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16374A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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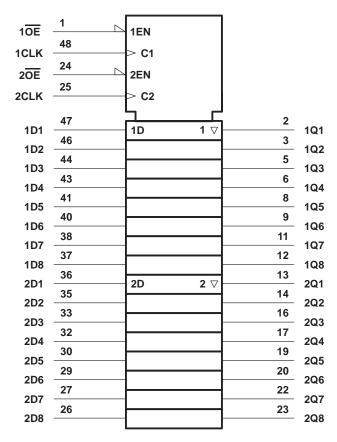


SCBS205C - MARCH 1993 - REVISED MAY 1997

FUNCTION TABLE (each flip-flop)

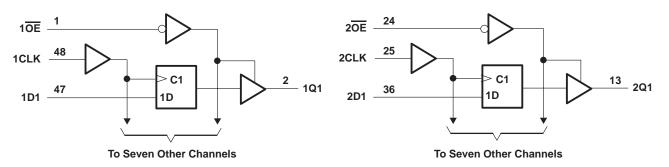
	INPUTS	OUTPUT	
ŌĒ	CLK	Q	
L	1	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q ₀
Н	Χ	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCBS205C - MARCH 1993 - REVISED MAY 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16374A	96 mA
SN74ABT16374A	128 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54ABT	16374A	SN74ABT	16374A	UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	Vcc	V
IOH	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SCBS205C - MARCH 1993 - REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	RAMETER	TEST O	ONDITIONS	1	T _A = 25°C	;	SN54ABT	16374A	SN74ABT1	16374A	UNIT
PAR	KAMETER	l lesi c	ONDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ _{\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\}		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
Vai		V00 - 45 V	I _{OL} = 48 mA			0.55		0.55			V
VOL		V _{CC} = 4.5 V I _{OL} = 64 mA				0.55*				0.55	V
V _{hys}					100						mV
IĮ		$V_{CC} = 0 \text{ to } 5.5 \text{ V}$	$V_1 = V_{CC}$ or GND			±1		±1		±1	μΑ
l _{OZPU} ‡	‡	$V_{CC} = 0 \text{ to } 2.1 \text{ V}_{O} = 0.5 \text{ to } 2.7 \text{ V}_{O}$	/, V, OE = X			±50		±50		±50	μΑ
l _{OZPD} ‡	‡	$V_{CC} = 2.1 \text{ V to } V_{O} = 0.5 \text{ to } 2.7$			±50		±50		±50	μА	
lozh		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$				10		10		10	μА
lozL		V _{CC} = 2.1 V to V _O = 0.5 V, OE				-10		-10		-10	μА
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX	Outputs high	V _{CC} = 5.5 V,	V _O = 5.5 V			50		50		50	μΑ
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
	Outputs high					2		2		2	
loo	Outputs low	V _{CC} = 5.5 V, I _O				72		72		72	mΑ
Icc	Outputs disabled	$V_I = V_{CC}$ or GN			2		2		2	IIIA	
ΔICC¶		V _{CC} = 5.5 V, Or Other inputs at V			1.5		1.5		1.5	mA	
Ci		V _I = 2.5 V or 0.5	V		3.5						pF
Co		$V_0 = 2.5 \text{ V or } 0.$	5 V		9.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} = T _A = 2	= 5 V, !5°C [#]	SN54ABT1	16374A	SN74ABT	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz
t _W	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	1.1		1.3		1.1		ns
th	Hold time, data after CLK↑	1.3		1.5		1.3		ns

[#]These values apply only to the SN74ABT16374A.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SCBS205C - MARCH 1993 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

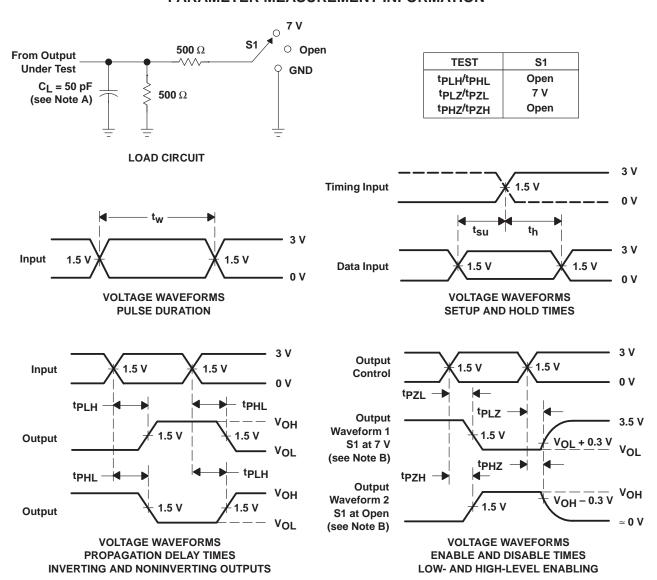
				SN54	ABT163	74A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	<u>'</u> ,	MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			150			150		MHz
^t PLH	CLK	Q	1.8	4.3	5.7	1.5	6.9	ns
^t PHL	OLK	Q	2.7	4.7	6.1	2.2	6.9	115
^t PZH	ŌĒ	Q	1.2	3.4	4.8	0.8	6.1	ns
t _{PZL}	OE	Q	1.6	3.5	4.9	1.2	5.5	115
^t PHZ	ŌĒ	Q	2.2	5.5	8.6	1.8	9.6	ns
t _{PLZ}	OL	Q	2.2	4.3	6.2	1.8	7.2	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			150			150		MHz
t _{PLH}	CLK	Q	1.8	4.3	5.4	1.8	6.2	ns
tPHL	OLK	Q	2.7	4.7	5.6	2.7	5.9	115
^t PZH	ŌĒ	Q	1.2	3.4	4.8	1.2	5.6	ns
tPZL	OE .	Q	1.6	3.5	4.7	1.6	5.3	115
t _{PHZ}	ŌĒ	Q	2.2	5.5	7.1	2.2	8.2	ns
tPLZ			2.2	4.3	5.8	2.2	6.6	115

SCBS205C - MARCH 1993 - REVISED MAY 1997

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9320101MXA	Active	Production	CFP (WD) 48	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9320101MX A SNJ54ABT16374A WD
SN74ABT16374ADGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADGGR.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADL	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADL.B	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADLR.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADLRG4	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SN74ABT16374ADLRG4.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16374A
SNJ54ABT16374AWD	Active	Production	CFP (WD) 48	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9320101MX A SNJ54ABT16374A WD

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ABT16374A, SN74ABT16374A:

Catalog: SN74ABT16374A

Military: SN54ABT16374A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 25-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16374ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT16374ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ABT16374ADLRG4	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

www.ti.com 25-Jul-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16374ADGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABT16374ADLR	SSOP	DL	48	1000	356.0	356.0	53.0
SN74ABT16374ADLRG4	SSOP	DL	48	1000	356.0	356.0	53.0

PACKAGE MATERIALS INFORMATION

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TUBE



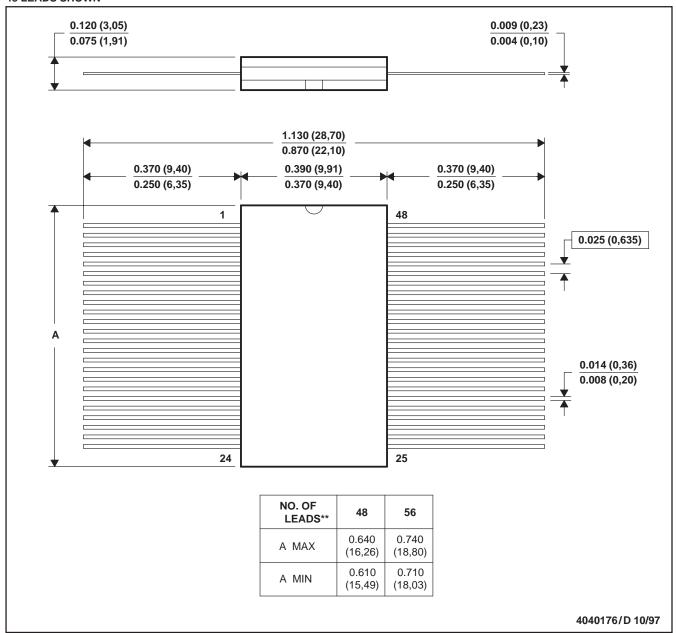
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT16374ADL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABT16374ADL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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